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Table of Contents

Smart Systems Integration – trends in the field of smart medtech systems 1

Thomas Gessner, Martina Vogel, Thomas Otto, Fraunhofer ENAS, Germany
Joerg Nestler, Chemnitz University of Technology, Germany

Conference Sessions

Session I: System integration and packaging

Development of 3D Integrated SiP using embedded active/passive chips in PCB and external parts 5

Arnaud Grivon, THALES Global Service, France

Hybrid assembly of micro scanner arrays with large aperture and their system integration 6

Thilo Sandner, Michael Wildenhain, Markus Schwarzenberg, Harald Schenk, Fraunhofer IPMS, Germany

Low temperature wafer bonding technology for RF based MEMS devices 14

Marco Haubold, Steffen Kurth, Thomas Gessner, Fraunhofer ENAS, Germany
Sascha Figur, Bernhard Schönlinner, EADS Germany, Germany

Session II: Advanced technology and reliability

Advances in Reliability Research by Means of Crack Avoidance Strategies 22

Bernd Michel, E. Auerswald, Fraunhofer, Germany
T. Winkler, Berliner Nanotest und Design, Germany
H. Shirangi, Robert Bosch, Germany
G. Wondrak, Daimler, Germany

Distortion Measurements and Simulations on Mechanically Stressed Bare Die MEMS Gyroscopes 27

Markus Dorwarth, Steven Kehrberg, Max Schellenberg, Holger Rank, Benjamin Schmidt, Robert Bosch, Germany
Jan Mehner, Chemnitz University of Technology, Germany

Inkjet-Printed Functionalities for Microfluidic Lab-on-a-Chip Systems 35

Erik Beckert, Oliver Pabst, Zhe Shu, Ramona Eberhardt, Andreas Tünnermann, Fraunhofer IOF, Germany
Jolke Perelaer, Ulrich Schubert, Friedrich-Schiller-University, Germany
Holger Becker, microfluidic ChipShop, Germany

Wafer-level technology for piezoresistive electro-mechanical transducer based on Carbon Nanotubes 43

Alexey Shaporin, Sascha Hermann, Christian Kaufmann, Stefan E. Schulz, Thomas Gessner, Sebastian Voigt, Jan Mehner, Steffen Hartmann, Bernhard Wunderle, Chemnitz University of Technology, Germany
Jens Bonitz, Fraunhofer ENAS, Germany

Session III: 3D-Integration and interconnect technologies I

Challenges and Methods for the Design of 3D-Integrated Smart Systems 50

Uwe Knöchel, Andy Heinig, Fraunhofer IIS/EAS, Germany

Photo-definable polyimide-based Flat UTCP technology for 3D-stacking application 58

T. Sterken, S. Priyabadini, M. Op de Beeck, J. Vanfleteren, Centre for Microsystems Technology, Belgium

Silicon Interposers with TSVs – A basis for Wafer Level 3D System Integration 66

Kai Zoschke, Fraunhofer IZM, Germany

Jürgen Wolf, Fraunhofer IZM-ASSID, Germany

Oswin Ehrmann, Klaus-Dieter Lang, Technical University of Berlin, Germany

Vertical Integration techniques for MEMS using HAR TSV 74

Lutz Hofmann, I. Schubert, R. Ecke, K. Gottfried, Fraunhofer ENAS, Germany

S. E. Schulz, T. Gessner, Chemnitz University of Technology, Germany

Hybrid microassembly for 3D integration and heterogeneous integration of microsystem – EU FP7 Project FAB2ASM 82

Quan Zhou, Aalto University, Finland

Session IV: Micro and nano systems and components

Compact double monochromator based on tunable MEMS gratings 90

Maurizio Tormen, Markus Lützelshwab, Branislav Timotijevic, Réal Ischer, Ross Stanley, Thomas Overstolz, Sylvain Grossmann, Jörg Pierer, Christian Bosshard, CSEM, Switzerland

Miniature Fourier transform infrared spectrometer for multi gas detection 98

Tatsuyuki Tanahashi, Takahito Ono, Tohoku University, Japan

Multi-sensors modules in SiGeMEMS technology 106

T. Sterken, M. Op de Beeck, H.A.C. Tilmans, A. Witvrouw, S. Severi, P. Helin, M. A. Erismis,

L. Haspelslagh, V. Rochus, R. F. Yazicioglu, S. Donnay, C Van Hoof X. Rottenberg, IMEC, Belgium

Sensors for Cyber Chemical Systems 114

Yvonne Joseph, Madlin Falk, Frederic Güth, Rosemarie Dittrich, Technical University Bergakademie Freiberg, Germany

Adaptive antenna tuners for mobile phones 122

Erwin Spits, K. Boyle, M.A. de Jongh, T. Bakker, S. Sato, A. van Bezooijen, Epcos Netherlands, the Netherlands

Session V: 3D-Integration and interconnect technologies II

Thin-film based stretchable electronics technologies 130

Rik Verplancke, Amir Jahanshahi, Tom Sterken, Dieter Cuypers, Jan Vanfleteren, Ghent University – IMEC, Belgium

Interflex: Reliable integration technologies for building a system-in-foil 138

Erwin Yacoub-George, Robert Faul, Karlheinz Bock, Fraunhofer EMFT, Germany

JEMSIP_3D: Major results & achievements from the project and exploitation thereof in future products 146

M. Jürgen Wolf, Fraunhofer IZM, Germany
H. Kapitza, Germany
K. Pressel, Infineon Technologies, Regensburg, Germany
J. Perrocheau, LCP's consultants, Trets, France
Y. De Maquille, Linxens, Mantes-la-Jolie, France
L. F. Tz. Kwakman, FEI Company, Eindhoven, The Netherlands
A. Rouzaud, CEA-Leti, Grenoble, France

InP-Si BiCMOS Hetero Integration for broadband radio links 155

Marco Lisker, IHP – Leibniz Institut für innovative Mikroelektronik, Germany

Session VI: Smart power, smart grids

Smart Energy Agents as an Enabler for Smart Distribution Grids 156

Michael Metzger, Andrei Szabo, Siemens, Germany

Optical Power Supply for Sensor Nodes in Intelligent Sensorial Materials 164

Christoph Budelmann, DFKI, Germany
Mike Bülters, Bremer Institut für angewandte Strahltechnik, Germany

Rechargeable Micro Fuel Cells as Power Supply for Smart Microsystems 170

Dominik Zimmermann, I. Freund, Micronas, Germany
J. Becker, C. Müller, H. Reinecke, University of Freiburg, Germany

ARTEMIS ME³Gas open source middleware platform inter-operability retrofit pilot 178

Brendan O' Flynn, Mike Hayes, Liam Moore, Cian O' Mathúna, Tyndall National Institute, Ireland
Emmanuel Frécon, Joakim Eriksson, Swedish Institute of Computer Science, Sweden
Peter Rosengren, Peeter Kool, CNet, Sweden
Alberto Fernandez, Sensing & Control, Spain

Session VII: Manufacturing technologies for smart integrated systems I

Flexible and Stretchable Electronics and Applications for Biomedical Devices 187

Dae-Hyeong Kim, Seoul National University, Korea

Integration techniques and applications of thin chips on low cost foil substrates 188

Daan van den Ende, A. Sridhar, R. Kusters, J. van den Brand, Holst Centre/TNO, the Netherlands
M. Cauwe, B. Vandecasteele, IMEC-CMST, Belgium

Multi-Sensor Stacking using Mold Embedding Processes 196

Karl-Friedrich Becker, T. Braun, K. Piefke, V. Bader, R. Aschenbrenner, Fraunhofer IZM, Germany
R. Kahle, S. Voges, T. Thomas, K.-D. Lang, Technical University Berlin, Germany

Development of a biocompatible encapsulation and interconnect technology for implantable electronics 204

Maaïke Op de Beeck, Karen Qian, Bishoy Morcos, Aleksander Radisic, Karl Malachowski, Chris Van Hoof, IMEC, Belgium

A hybrid Elastomer-MEMS actuator for a tactile graphical display 212

Jacek Baborowski, S. Mouaziz, T. Overstolz, Ph. Niedermann, CSEM, Switzerland
S. Fazekas, A. Ágoston, MFKK, Hungary
G. Martínez, CRIC, Spain
Y. Leung-Ki, S. Gamper, Karmic, Switzerland
E. Schäfer, U. Grotz, Metec, Germany

Session VIII: Smart medtech systems and systems for prognostic health

Novel piezoelectric harvester for cardiac implants: Design, Optimisation & Fabrication 220

Renzo Dal Molin, Sorin CRM, France
An Nguyen-Dinh, Claire Bantignies, Vermon, France
Sébastien Boisseau, CEA-Leti, France

Wireless Smart Glove for arthritis rehabilitation 228

Brendan O'Flynn, Javier Torres Sanchez, Philip Angove, Tyndall National Institute, Ireland
James Connolly, Joan Condell, Kevin Curran, University of Ulster, Ireland

Wearable Smart Systems for Personal Healthcare and Lifestyle 236

Ruud Vullers, Julien Penders, Sywert Brongersma, Jacqueline Wijsman, Marco Altini, Chris Van Hoof, Holst Centre, the Netherlands

A Flexible Micro-Electrode Array with an Embedded Flexible CMOS-Chip for Medical Applications 244

Nadine Winkin, Wilfried Mokwa, RWTH Aachen, Germany
Uta Gierth, Alexander Michaelis, Thomas Rabbow, Fraunhofer IKTS, Germany

The integrated micro optical sensor for photometry and fluorescence applications 252

Martin Baca, Andreas Schober, Xuan Ma, Adrian Grewe, Ilmenau University of Technology, Germany
Martin Schaedel, Olaf Brodersen, Matthias Will, CiS, Germany

Session IX: Manufacturing technologies for smart integrated systems II

pMUT for High Intensity Focused Ultrasound 259

An Nguyen-Dinh, Etienne Flesch, Cyril Meynier, Vermon, France
Dag Wang, Frode Tyholdt, Andreas Vogl, Hannah Tofteberg, Niels Peter Østbø, SINTEF, Norway

Integration of Multi-level MOEMS Structures on CMOS for Spatial Light Modulators 267

Martin Friedrichs, Matthias List, Michael Müller, Fraunhofer IPMS, Germany

Absolute Pressure Sensors made by Anodic Bonding 275

Konstanze Schmidt, Uwe Schwarz, X-FAB Semiconductor Foundries, Germany

Manufacturing Technologies for Integrated Smart Systems: a Primer 283

Marc Desmulliez, Heriot-Watt University, United Kingdom
David Topham, Brunel University, United Kingdom

Session X: Micro-Nano-Bio systems applications

Sensors for human-machine-interfaces in smart medical systems – Integration challenges and solutions 284

Dirk Fengels, Thomas Burch, CSEM, Switzerland
Joeri Gredig, Swissrehamed, Switzerland
Thomas Maeder, Caroline Jacq, EPFL, Switzerland

Microfluidic integration: what options do we have and what does it mean? 292

Henne van Heeren, enablingMNT, the Netherlands
Patric Salomon, enablingMNT, Germany

Cellenc: human cell encapsulation in closed loop microfluidic chip 300

Patrick Boisseau, S. Morales, J. Berthier, P.-Y. Benhamou, A. Comte Bellemin, F. Boizot, P. Caillat, F. Rivera, CEA, France

Self-powered microfluidic platform for autonomous amperometric sensing 305

Juan Pablo Esquivel, Centre Nacional de Microelectrónica (CNM-CSIC), Spain

Session XI: Advanced sensor technologies / Sensor networks

MEMS Technology for Consumer Electronics 306

Stefan Finkbeiner, Bosch Sensortec, Germany

Smart MEMS systems for automotive safety 307

Marc Osajda, Freescale Halbleiter, Germany

Autonomous Visual Sensors for safety and security 308

Zeev Smilansky, Emza Visual Sense, Israel

Massimo Gottardi, Fondazione Bruno Kessler, Italy

Wireless Sensors Networks in Electromagnetically and Physically Hostile Environments 316

Anders Rydberg, Mathias Gruden, Magnus Jobs, University of Uppsala, Sweden

Session XII

Technology Clusters and Their Role in the Commercialization of Micro and Nanosystems 324

Roger H. Grace, Roger Grace Associates, USA

Poster Session

An intelligent modular tool for the monitoring and control of high efficient grinding processes 331

Oliver Adams, Laboratory for Machine Tools and Production Engineering, Germany

Generic process for low-cost InP integrated photonics in industrial foundries 332

Luc Augustin, Huub Ambrosius, Peter Thijs, Mike Wale, Meint Smit, TU Eindhoven, the Netherlands

Norbert Grote, Fraunhofer HHI, Germany

Robot Manipulator with emergent Behaviour supported by a Smart Sensorial Material and Agent Systems 336

Stefan Bosse, Florian Pantke, Stefan Edelkamp, University Bremen, Germany

CO₂ sensor system for mobile application 340

Jamila Boudaden, F. Wenninger, S. Kibler, K. Neumeier, R. Faul, A. Drost, D. Bonfert, U. Schaber,

L. Meixner, H-E. Endres, I. Eisele, Fraunhofer EMFT, Germany

K. Rose, Fraunhofer ISC, Germany

New solution addresses energy measurement challenges related to wireless devices driven by microharvester 344

Carlo Canziani, Agilent Technologies, Italy

Investigations on Eutectic Bonding of Polyimide Structures for MEMS Applications 346

Tom Creutzburg, Johannes Rittinger, Lutz Rissing, Srećko Cvetković, Leibniz University Hannover,

Germany

Technology Development for Packaging of the GMR-Sensor via Eutectic Bonding 350

Srećko Cvetkovic, Rahel Kruppe, Johannes Rittinger, Lutz Rissing, Leibniz University Hannover,

Germany

Picosecond Laser Micromachining in the context of MEMS/NEMS applications 354

Tom Enderlein, Christian Helke, Karla Hiller, Jörg Nestler, Technical University Chemnitz, Germany

Martin Schüller, Sascha Geidel, Thomas Otto, Thomas Gessner, Fraunhofer ENAS, Germany

Investigation of micro structuring and magnetizing of spintronic layer stacks using laser irradiation 358

Horst Exner, Isabel Berthold, Matthias Müller, Robby Ebert, Hochschule Mittweida, Germany

Senoy Thomas, Patrick Matthes, Chemnitz University of Technology, Germany

Multi-sensor module for the measurement of pressure, temperature, flow rate and concentration in micro reaction technology 362

Thomas Frank, Andrea Cyriax, Sebastian Pobering, CiS Research institute for micro sensors and photovoltaic, Germany

Miniaturized frequency doubled DPSS assembled using solderjet bumping technology 366

Marte Gilaberte Basset, D. Guilhot, S. Ferrando, P. Ribes, D. Montes, M. Galan, Monocrom, Spain
T. Burkhardt, E. Beckert, M. Hornaff, Fraunhofer Institute for Applied Optics and Precision Engineering, Germany

SmartSenior – a multifunctional wristband supports living at home 382

Julia Günther, Jin-U Kim, Fraunhofer IZM, DE

Barriers to the Successful Commercialization of MEMS: the 2012 MEMS Industry Commercialization Report Card 370

Roger H. Grace, Roger Grace Associates, USA

Stress Relief Technologies for Laser Diced Wafers 374

Jürgen Grafe, S. Mimietz, M. Lorenz, M. Schima, Fraunhofer IZM, Germany

Actuator net design for morphing wing structure 378

André Gratias, Martin Schueller, Matthias Lipowski, Fraunhofer ENAS, Germany
Ignazio Dimino, CIRA, Italy

Studies on the piezoresistive effect in MOS transistors for use in integrated MEMS sensors 385

Sven Haas, Michael Schramm, Kay-Uwe Loebel, Steffen Heinz, Danny Reuter, Andreas Bertz, John Thomas Horstmann, Thomas Geßner, Chemnitz University of Technology, Germany

Inkjet Printing of Microsieves and Reinforcing Patterns for Fragile Microsieves 389

Jens Hammerschmidt, Peter Ueberfuhr, Reinhard R. Baumann, Kerstin Gläser, Werner A. Goedel, Technical University Chemnitz, Germany
Franziska M. Wolf, Friedrich-Schiller-Universität Jena, Germany

Tomorrow's Telemetry Today: Citizen Observatory Approach with Micro Sensors and Smart Prognostics 393

Dieter Hayn, AIT Austrian Institute of Technology, Austria
Mike Kobernus, Norwegian Institute for Air Research, Norway

Laterally stacked organic devices fabricated by trench technology 397

Karla Hiller, Danny Reuter, Sreetama Banerjee, Michael Fronk, Georgeta Salvan, Dietrich R. T. Zahn, Thomas Gessner, Technical University Chemnitz, Germany

Fiber Optics in Arc Flash Detection Applications 401

Alek Indra, Avago Technologies, Singapore

Cyber Chemical Systems – Sensors and Information Processing 405

Yvonne Joseph, TU Bergakademie Freiberg, Germany
Daniela Nicklas, University of Oldenburg, Germany

Integration of MEMS/NEMS models at the system level using VHDL-AMS 409

Vladimir Kolchuzhin, Jan Mehner, Shende Milind, Erik Markert, Ulrich Heinkel, Christian Wagner, Technical University Chemnitz, Germany
Thomas Gessner, Fraunhofer ENAS, Germany

Autonomous Micro-platform for Multi-sensors (AMM) for wireless monitoring 413

Philippe Laurent, N. Maillard, S. Stoukatch, F. Axisa, J. Destiné, MICROSYS University of Liege, Belgium

Design and simulation of nanomaterial-enhanced LTCC integrated inductors 419

Yu-Ching Lin, Shuji Tanaka, Masayoshi Esashi, Tohoku University, Japan
Felix Gabler, Thomas Gessner, Fraunhofer ENAS, Germany

System Design of Double Wall Synthetic Jet Actuators 423

Mathias Lipowski, Martin Schueller, Fraunhofer ENAS, Germany
Robert Schulze, Chemnitz University of Technology, Germany

Influence of DMSO and MWCNTs addition on the thermoelectric properties of PEDOT:PSS Thin Films 427

Jinji Luo, Petra Streit, Thomas Gessner, Technical University Chemnitz, Germany
Detlef Billep, Thomas Otto, Fraunhofer ENAS, Germany

A Specification tool for Nanosystems 431

Erik Markert, Milind Shende, Matthias Sauppe, Thomas Horn, Sven Quinger, Ulrich Heinkel, Technical University Chemnitz, Germany

Integration of a position photodiode for a micro laser tracker system 435

Eric Markweg, Tran Trung Nguyen, Christoph Ament, Martin Hoffmann, Technical University Ilmenau, Germany
Martin Schädel, Olaf Brodersen, CiS Institut für Mikrosensorik und Photovoltaik, Germany

Optical sensor for flow measurements in capillaries 439

Ralf Müller, Olaf Brodersen, CiS Research Institute for Micro Sensors and Photovoltaic, Germany
Dieter Petrak, Ingenieurbüro FlowSensor, Germany

Comparison of various polymer-based dry electrodes for high quality EEG/ECG measurements 443

Maike Op de Beeck, Yun-Hsuan Chen, C. Van Hoof, IMEC, Belgium
L. Vanderheyden, Datwyler Sealing Solutions, Belgium

Development of Novel Micro Conveyors by Using Piezoelectric Vibration Stages 447

Chi Hsiang Pan, National Chin-Yi University of Technology, Taiwan

Via-Last technology for the interconnection of flash and processor chip for mobile applications 451

René Puschmann, Mathias Böttcher, Peggy John, Irene Bartussek, Charles Manier, Kai Zoschke, Jürgen Grafe, Fraunhofer IZM, Germany
Michael Ziesmann, NXP Semiconductors Germany, Germany

M&NEMS: a technological platform for 10-axis sensor 455

Philippe Robert, P. Rey, A. Berthelot, G. Jourdan, Y. Deimerly, CEA-Léti, France
S. Louwers, J. Bon, F-X. Boillot, Joël Collet, Tronics, France

Package Characterization with Stress Chip Measurements for Health Monitoring 459

Florian Rost, F. Schindler-Saefkow, A. Otto, B. Michel, S. Rzepka, Fraunhofer ENAS, Germany

Joint Technology Initiative Clean Sky – Aims for greener Aviation 464

Martin Schueller, E. Kaulfersch, M. Lipowski, Fraunhofer ENAS, Germany

Inkjet-printed electronics: Transfer from lab to fab manufacturing 468

Enrico Sowade, Kalyan Yoti Mitra, Reinhard R. Baumann, Technical University Chemnitz, Germany
Henrique Leonel Gomes, Universidade do Algarve, Portugal

Evaluation of the Generated Energy by Non-Harmonic Movement of a Permanent Magnet Near a Coil 472

Nobby Stevens, Lieven De Strycker, Davy Mercy, KU Leuven, Belgium

Optimization of MEMS/NEMS for reliable resonance frequencies 476

Chris Stoeckel, Kay Hofmann, Technical University Chemnitz, Germany
Roman Forke, Detlef Billep, Thomas Gessner, Fraunhofer ENAS, Germany

System reliability as a key for managing complex requirements, such as robust design of microsystems 480

Stefan Straube, Daniel Hahn, Kathleen Jerchel, Andreas Middendorf, Olaf Wittler, Klaus-Dieter Lang, Fraunhofer IZM, Germany

Bio-Chemical-Sensors Array Impedance Spectroscopy Chip 484

Drago Strle, University of Ljubljana, Slovenia

Integration and fabrication of PZT and metallic glass films for micro-mirror device 488

Yao-Chuan Tsai, Jae-Wung Lee, Yu-Ching Lin, Masayoshi Esashi, Tohoku University, Japan
Takayuki Naono, Takamichi Fujii, Fujifilm Corporation, Japan
Thomas Gessner, Fraunhofer ENAS, Germany

Capacitive Silicon-Microphone and its mechanical and electro-acoustical properties 492

Robert Wieland, Jamila Boudaden, Detlef Bonfert, Peter Iskra, Ignaz Eisele, Fraunhofer EMFT, Germany
Gregor Feiertag, Munich University of applied Sciences, Germany

Adapted printed battery development for driving a smart miniaturised cholesterol sensing system 496

Andreas Willert, Reinhard, R. Baumann, Fraunhofer ENAS, Germany
Michael Espig, Enrico Sowade, Technical University Chemnitz, Germany

Through Silicon via Interposer for 3D Integration 500

Jürgen Wolf, Fraunhofer IZM, Germany

Development of a 40 Watts 5 kV converter using Piezoelectric Transformer for Rheoelectrical damper application 501

Yujia Yang, Matthias Radecker, Stephan Guttowski, Klaus-Dieter Lang, Fraunhofer IZM, Germany
Bruno Fontana da Silva, Lucas Vizzotto Bellinaso, Raffael Engleitner, Federal University of Santa Maria, Brazil
Alfredo Vazquez Carazo, Micromechatronics, USA

2D semiconductors: New innovative platform for the next generation of advanced functional systems 505

Serge Zhuiykov, CSIRO, Australia

Tutorial

Future opportunities for SME in Smart Systems R+I N/A

Anna Puig-Centelles, STARLAB, Spain
Luis Fonseca, CNM-CSIC, Spain
Chris Merveille, IK4-IKERLAN, Spain
Thomas Koehler, VDI-VDE, Germany

Keynote-Sessions

Active control in microfluidic systems N/A

Jaap den Toonder, Philips Research Laboratories, the Netherlands

Special sessions by EPoSS

A new strategic research agenda for smart systems integration: markets, technologies, processes N/A

Implementing the new EPoSS SRA: policy recommendations and industrial roll-out N/A

US Session

MEMS Industry Group